

Single and Dual Precision, 17 MHz, Low Noise, CMOS Input Amplifiers

Check for Samples: [LMP7711](#)

FEATURES

- Unless otherwise noted, typical values at $V_S = 5V$.
- Input offset voltage $\pm 150 \mu V$ (max)
- Input bias current 100 fA
- Input voltage noise 5.8 nV/ \sqrt{Hz}
- Gain bandwidth product 17 MHz
- Supply current (LMP7711) 1.15 mA
- Supply current (LMP7712) 1.30 mA
- Supply voltage range 1.8V to 5.5V

- THD+N @ $f = 1 \text{ kHz}$ 0.001%
- Operating temperature range $-40^\circ C$ to $125^\circ C$
- Rail-to-rail output swing
- Space saving TSOT23 package (LMP7711)
- 10-pin MSOP package (LMP7712)

APPLICATIONS

- Active filters and buffers
- Sensor interface applications
- Transimpedance amplifiers

DESCRIPTION

The LMP7711/LMP7712 are single and dual low noise, low offset, CMOS input, rail-to-rail output precision amplifiers with a high gain bandwidth product and an enable pin. The LMP7711/LMP7712 are part of the LMP™ precision amplifier family and are ideal for a variety of instrumentation applications.

Utilizing a CMOS input stage, the LMP7711/LMP7712 achieve an input bias current of 100 fA, an input referred voltage noise of 5.8 nV/ \sqrt{Hz} , and an input offset voltage of less than $\pm 150 \mu V$. These features make the LMP7711/LMP7712 superior choices for precision applications.

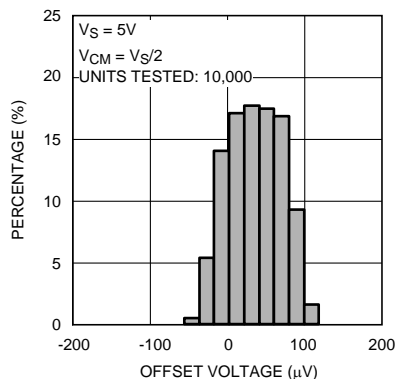
Consuming only 1.15 mA of supply current, the LMP7711 offers a high gain bandwidth product of 17 MHz, enabling accurate amplification at high closed loop gains.

The LMP7711/LMP7712 have a supply voltage range of 1.8V to 5.5V, which makes these ideal choices for portable low power applications with low supply voltage requirements. In order to reduce the already low power consumption the LMP7711/LMP7712 have an enable function. Once in shutdown, the LMP7711/LMP7712 draw only 140 nA of supply current.

The LMP7711/LMP7712 are built with National's advanced VIP50 process technology. The LMP7711 is offered in a 6-pin TSOT23 package and the LMP7712 is offered in a 10-pin MSOP.

Typical Performance

Figure 1. Offset Voltage Distribution



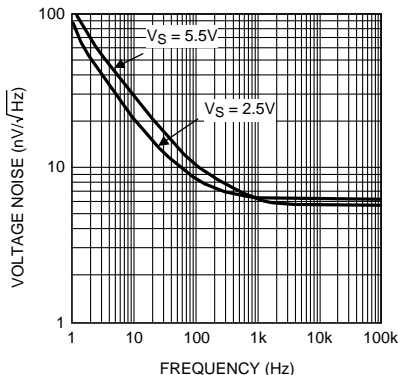
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LMP is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2005–2008, Texas Instruments Incorporated

Figure 2. Input Referred Voltage Noise

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾

ESD Tolerance ⁽²⁾	
Human Body Model	2000V
Machine Model	200V
Charge-Device Model	1000V
V_{IN} Differential	$\pm 0.3V$
Supply Voltage ($V_S = V^+ - V^-$)	6.0V
Voltage on Input/Output Pins	$V^+ +0.3V, V^- -0.3V$
Storage Temperature Range	$-65^{\circ}C$ to $150^{\circ}C$
Junction Temperature ⁽³⁾	$+150^{\circ}C$
Soldering Information	
Infrared or Convection (20 sec)	$235^{\circ}C$
Wave Soldering Lead Temp. (10 sec)	$260^{\circ}C$

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Tables.
- (2) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (3) The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$. All numbers apply for packages soldered directly onto a PC Board.

Operating Ratings ⁽¹⁾

Temperature Range ⁽²⁾	$-40^{\circ}C$ to $125^{\circ}C$
Supply Voltage ($V_S = V^+ - V^-$)	
$0^{\circ}C \leq T_A \leq 125^{\circ}C$	1.8V to 5.5V
$-40^{\circ}C \leq T_A \leq 125^{\circ}C$	2.0V to 5.5V
Package Thermal Resistance (θ_{JA}) ⁽²⁾	
6-Pin TSOT23	$170^{\circ}C/W$
10-Pin MSOP	$236^{\circ}C/W$

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Tables.
- (2) The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$. All numbers apply for packages soldered directly onto a PC Board.

2.5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for $T_A = 25^\circ\text{C}$, $V^+ = 2.5\text{V}$, $V^- = 0\text{V}$, $V_O = V_{CM} = V^+/2$, $V_{EN} = V^+$. **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
V_{OS}	Input Offset Voltage			± 20	± 180 ± 480	μV
$TC\ V_{OS}$	Input Offset Voltage Temperature Drift (3) (4)	LMP7711	-1.75	-1	± 4	$\mu\text{V}/^\circ\text{C}$
		LMP7712				
I_B	Input Bias Current	$V_{CM} = 1.0\text{V}$ (5) (4)	$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$	0.05	1 25	pA
			$-40^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$	0.05	1 100	
I_{OS}	Input Offset Current	$V_{CM} = 1.0\text{V}$ (4)		0.006	0.5 50	pA
CMRR	Common Mode Rejection Ratio	$0\text{V} \leq V_{CM} \leq 1.4\text{V}$	83 80	100		dB
PSRR	Power Supply Rejection Ratio	$2.0\text{V} \leq V^+ \leq 5.5\text{V}$ $V^- = 0\text{V}$, $V_{CM} = 0$	85 80	100		dB
		$1.8\text{V} \leq V^+ \leq 5.5\text{V}$ $V^- = 0\text{V}$, $V_{CM} = 0$	85	98		
CMVR	Common Mode Voltage Range	CMRR $\geq 80\text{ dB}$ CMRR $\geq 78\text{ dB}$	-0.3 -0.3		1.5 1.5	V
A_{VOL}	Open Loop Voltage Gain	LMP7711, $V_O = 0.15$ to 2.2V $R_L = 2\text{ k}\Omega$ to $V^+/2$	88 82	98		dB
		LMP7712, $V_O = 0.15$ to 2.2V $R_L = 2\text{ k}\Omega$ to $V^+/2$	84 80	92		
		LMP7711, $V_O = 0.15$ to 2.2V $R_L = 10\text{ k}\Omega$ to $V^+/2$	92 88	110		
		LMP7712, $V_O = 0.15$ to 2.2V $R_L = 10\text{ k}\Omega$ to $V^+/2$	90 86	95		
V_{OUT}	Output Voltage Swing High	$R_L = 2\text{ k}\Omega$ to $V^+/2$		25	70 77	mV from either rail
		$R_L = 10\text{ k}\Omega$ to $V^+/2$		20	60 66	
	Output Voltage Swing Low	$R_L = 2\text{ k}\Omega$ to $V^+/2$		30	70 73	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$		15	60 62	
I_{OUT}	Output Current	Sourcing to V^- $V_{IN} = 200\text{ mV}$ (6)	36 30	52		mA
		Sinking to V^+ $V_{IN} = -200\text{ mV}$ (6)	7.5 5.0	15		
I_S	Supply Current	LMP7711 Enable Mode $V_{EN} \geq 2.1$		0.95	1.30 1.65	mA
		LMP7712 (per channel) Enable Mode $V_{EN} \geq 2.1$		1.10	1.50 1.85	
		Shutdown Mode (per channel) $V_{EN} \leq 0.4$		0.03	1 4	μA

- (1) Limits are 100% production tested at 25°C . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (3) Offset voltage average drift is determined by dividing the change in V_{OS} at the temperature extremes by the total temperature change.
- (4) This parameter is guaranteed by design and/or characterization and is not tested in production.
- (5) Positive current corresponds to current flowing into the device.
- (6) The short circuit test is a momentary open loop test.

2.5V Electrical Characteristics (continued)

Unless otherwise specified, all limits are guaranteed for $T_A = 25^\circ\text{C}$, $V^+ = 2.5\text{V}$, $V^- = 0\text{V}$, $V_O = V_{CM} = V^+/2$, $V_{EN} = V^+$. **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
SR	Slew Rate	$A_V = +1$, Rising (10% to 90%)		8.3		V/ μs
		$A_V = +1$, Falling (90% to 10%)		10.3		
GBW	Gain Bandwidth			14		MHz
e_n	Input Referred Voltage Noise Density	$f = 400\text{ Hz}$		6.8		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		5.8		
i_n	Input Referred Current Noise Density	$f = 1\text{ kHz}$		0.01		$\text{pA}/\sqrt{\text{Hz}}$
t_{on}	Turn-on Time			140		ns
t_{off}	Turn-off Time			1000		ns
V_{EN}	Enable Pin Voltage Range	Enable Mode	2.1	2 - 2.5		V
		Shutdown Mode		0 - 0.5	0.4	
I_{EN}	Enable Pin Input Current	$V_{EN} = 2.5\text{V}$ ⁽⁵⁾		1.5	3.0	μA
		$V_{EN} = 0\text{V}$ ⁽⁵⁾		0.003	0.1	
THD+N	Total Harmonic Distortion + Noise	$f = 1\text{ kHz}$, $A_V = 1$, $R_L = 100\text{ k}\Omega$ $V_O = 0.9\text{ V}_{PP}$		0.003		%
		$f = 1\text{ kHz}$, $A_V = 1$, $R_L = 600\Omega$ $V_O = 0.9\text{ V}_{PP}$		0.004		

5V Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for $T_A = 25^\circ\text{C}$, $V^+ = 5\text{V}$, $V^- = 0\text{V}$, $V_{CM} = V^+/2$, $V_{EN} = V^+$. **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
V_{OS}	Input Offset Voltage			± 10	± 150 ± 450	μV
$TC\ V_{OS}$	Input Offset Voltage Temperature Drift (3) (4)	LMP7711	-1.75	-1	± 4	$\mu\text{V}/^\circ\text{C}$
		LMP7712				
I_B	Input Bias Current	$V_{CM} = 2.0\text{V}$ (5) (4)	$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$	0.1	1 25	pA
			$-40^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$	0.1	1 100	
I_{OS}	Input Offset Current	$V_{CM} = 2.0\text{V}$ (4)		0.01	0.5 50	pA
CMRR	Common Mode Rejection Ratio	$0\text{V} \leq V_{CM} \leq 3.7\text{V}$	85 82	100		dB
PSRR	Power Supply Rejection Ratio	$2.0\text{V} \leq V^+ \leq 5.5\text{V}$ $V^- = 0\text{V}$, $V_{CM} = 0$	85 80	100		dB
		$1.8\text{V} \leq V^+ \leq 5.5\text{V}$ $V^- = 0\text{V}$, $V_{CM} = 0$	85	98		
CMVR	Common Mode Voltage Range	CMRR $\geq 80\text{ dB}$ CMRR $\geq 78\text{ dB}$	-0.3 -0.3		4 4	V
A_{VOL}	Open Loop Voltage Gain	LMP7711, $V_O = 0.3$ to 4.7V $R_L = 2\text{ k}\Omega$ to $V^+/2$	88 82	107		dB
		LMP7712, $V_O = 0.3$ to 4.7V $R_L = 2\text{ k}\Omega$ to $V^+/2$	84 80	90		
		LMP7711, $V_O = 0.3$ to 4.7V $R_L = 10\text{ k}\Omega$ to $V^+/2$	92 88	110		
		LMP7712, $V_O = 0.3$ to 4.7V $R_L = 10\text{ k}\Omega$ to $V^+/2$	90 86	95		
V_{OUT}	Output Voltage Swing High	$R_L = 2\text{ k}\Omega$ to $V^+/2$		32	70 77	mV from either rail
		$R_L = 10\text{ k}\Omega$ to $V^+/2$		22	60 66	
	Output Voltage Swing Low	$R_L = 2\text{ k}\Omega$ to $V^+/2$ (LMP7711)		42	70 73	
		$R_L = 2\text{ k}\Omega$ to $V^+/2$ (LMP7712)		50	75 78	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$		20	60 62	
I_{OUT}	Output Current	Sourcing to V^- $V_{IN} = 200\text{ mV}$ (6)	46 38	66		mA
		Sinking to V^+ $V_{IN} = -200\text{ mV}$ (6)	10.5 6.5	23		

- (1) Limits are 100% production tested at 25°C . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (3) Offset voltage average drift is determined by dividing the change in V_{OS} at the temperature extremes by the total temperature change.
- (4) This parameter is guaranteed by design and/or characterization and is not tested in production.
- (5) Positive current corresponds to current flowing into the device.
- (6) The short circuit test is a momentary open loop test.

5V Electrical Characteristics (continued)

Unless otherwise specified, all limits are guaranteed for $T_A = 25^\circ\text{C}$, $V^+ = 5\text{V}$, $V^- = 0\text{V}$, $V_{\text{CM}} = V^+/2$, $V_{\text{EN}} = V^+$. **Boldface** limits apply at the temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
I_S	Supply Current	LMP7711 Enable Mode $V_{\text{EN}} \geq 4.6$		1.15	1.40 1.75	mA
		LMP7712 (per channel) Enable Mode $V_{\text{EN}} \geq 4.6$		1.30	1.70 2.05	
		Shutdown Mode $V_{\text{EN}} \leq 0.4$ (per channel)		0.14	1 4	μA
SR	Slew Rate	$A_V = +1$, Rising (10% to 90%)	6.0	9.5		$\text{V}/\mu\text{s}$
		$A_V = +1$, Falling (90% to 10%)	7.5	11.5		
GBW	Gain Bandwidth			17		MHz
e_n	Input Referred Voltage Noise Density	$f = 400\text{ Hz}$		7.0		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		5.8		
i_n	Input Referred Current Noise Density	$f = 1\text{ kHz}$		0.01		$\text{pA}/\sqrt{\text{Hz}}$
t_{on}	Turn-on Time			110		ns
t_{off}	Turn-off Time			800		ns
V_{EN}	Enable Pin Voltage Range	Enable Mode	4.6	4.5 – 5		V
		Shutdown Mode		0 – 0.5	0.4	
I_{EN}	Enable Pin Input Current	$V_{\text{EN}} = 5\text{V}$ (5)		5.6	10	μA
		$V_{\text{EN}} = 0\text{V}$ (5)		0.005	0.2	
THD+N	Total Harmonic Distortion + Noise	$f = 1\text{ kHz}$, $A_V = 1$, $R_L = 100\text{ k}\Omega$ $V_O = 4\text{ V}_{\text{PP}}$		0.001		%
		$f = 1\text{ kHz}$, $A_V = 1$, $R_L = 600\Omega$ $V_O = 4\text{ V}_{\text{PP}}$		0.004		

Connection Diagram

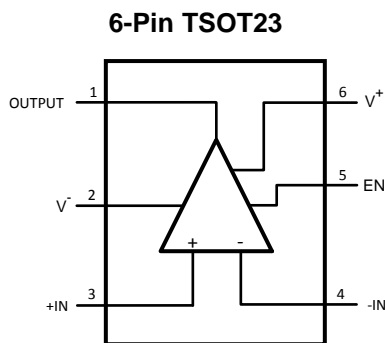


Figure 3. Top View

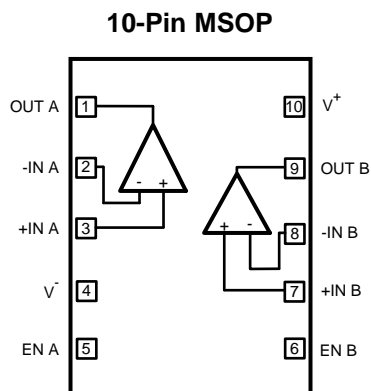
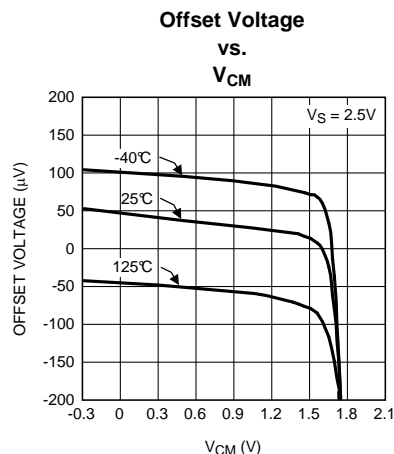
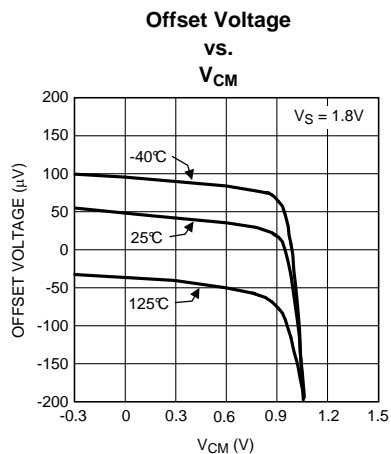
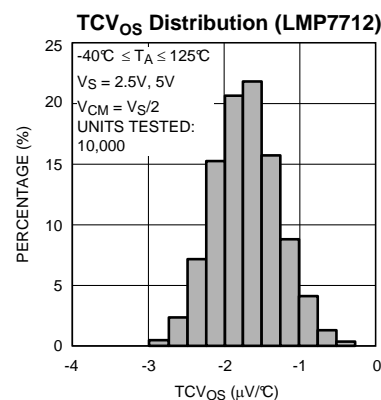
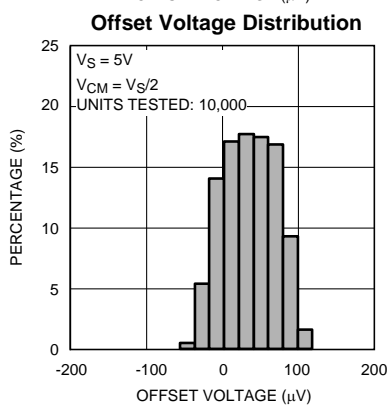
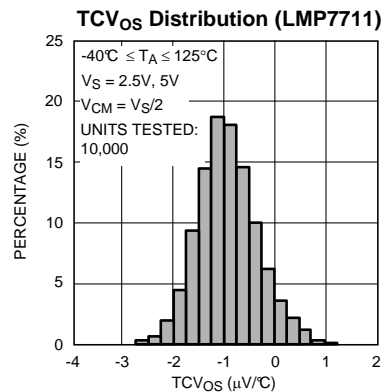
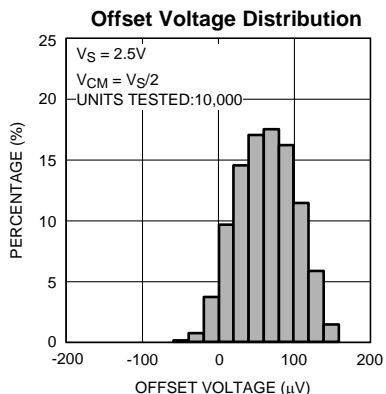


Figure 4. Top View

Typical Performance Characteristics

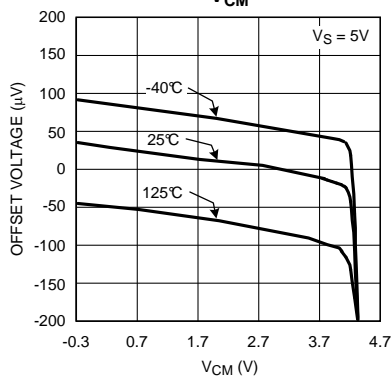
Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.



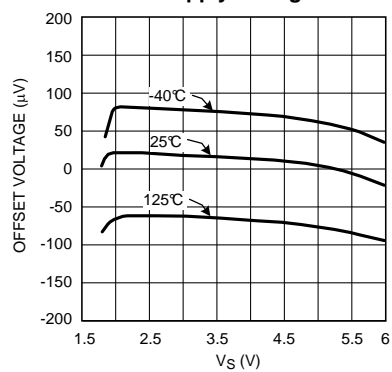
Typical Performance Characteristics (continued)

Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.

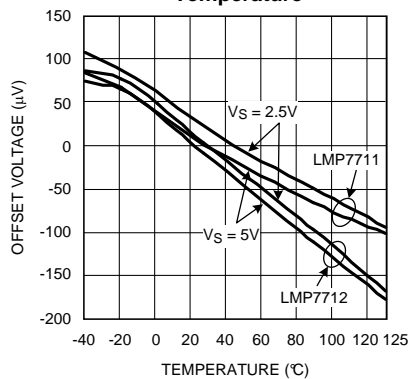
**Offset Voltage
vs.
 V_{CM}**



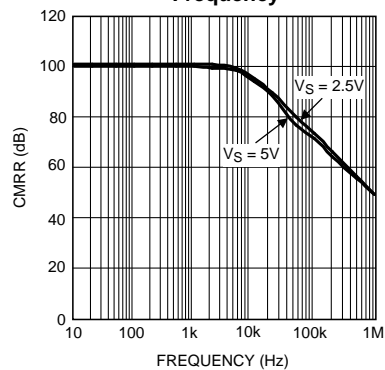
**Offset Voltage
vs.
Supply Voltage**



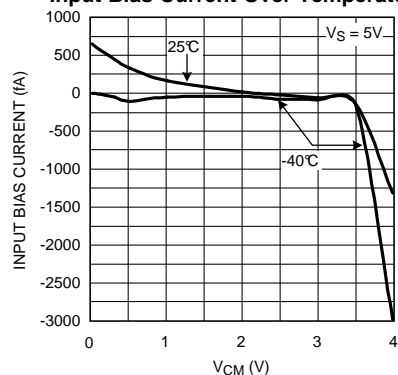
**Offset Voltage
vs.
Temperature**



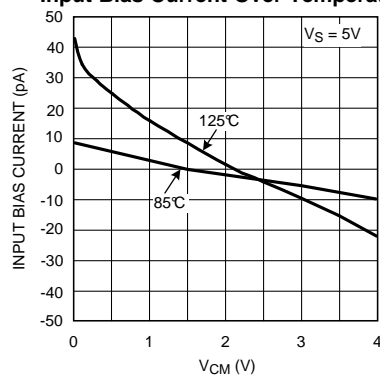
**CMRR
vs.
Frequency**



Input Bias Current Over Temperature

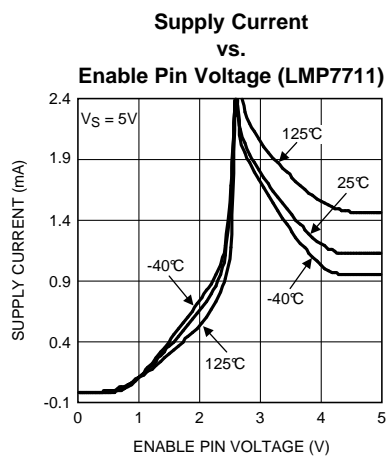
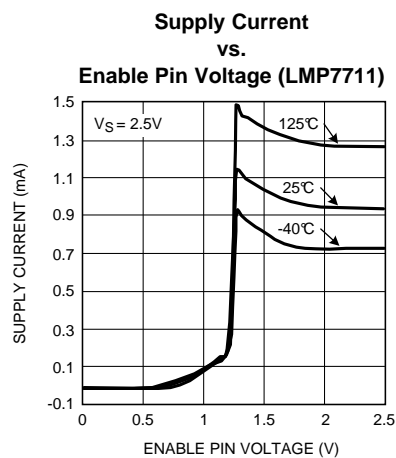
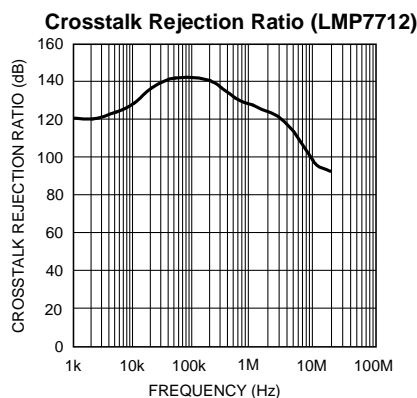
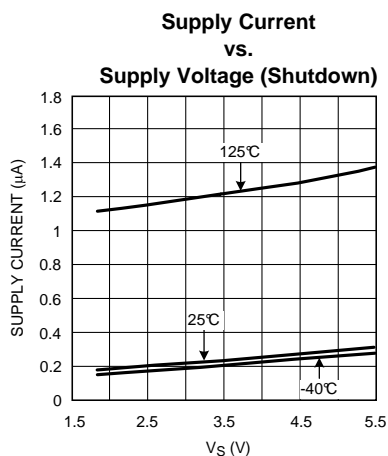
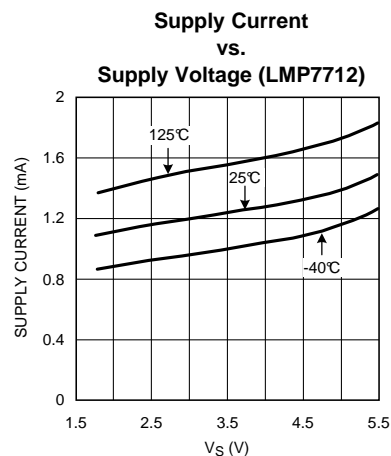
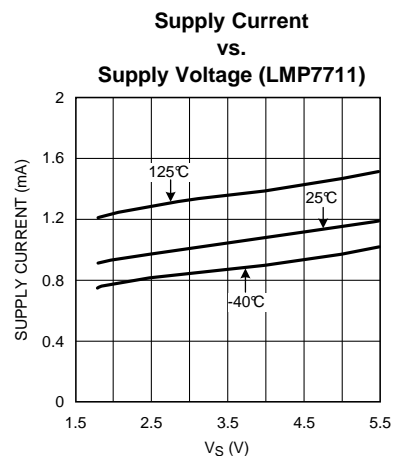


Input Bias Current Over Temperature



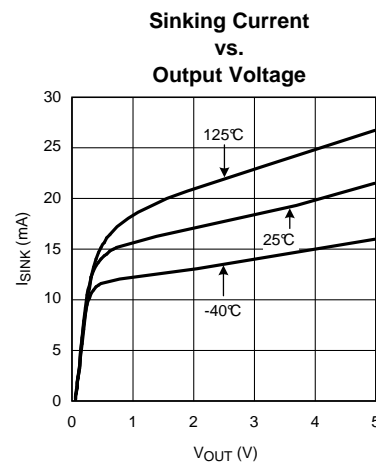
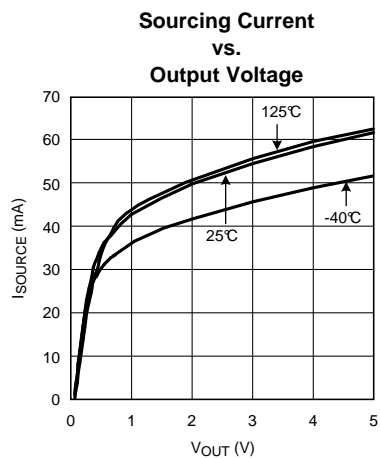
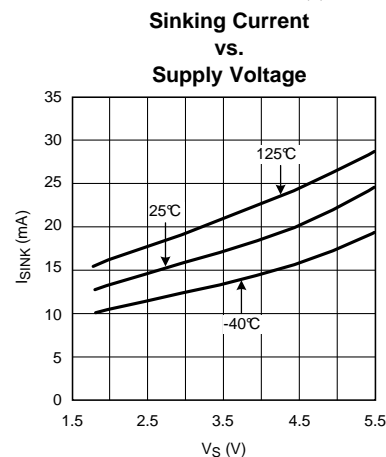
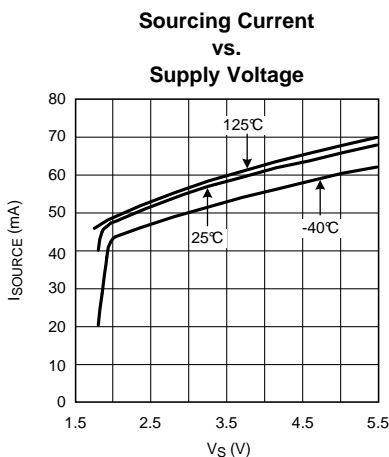
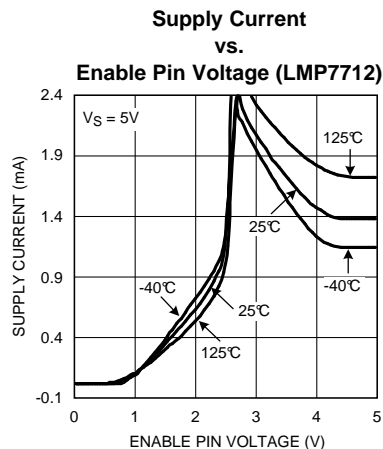
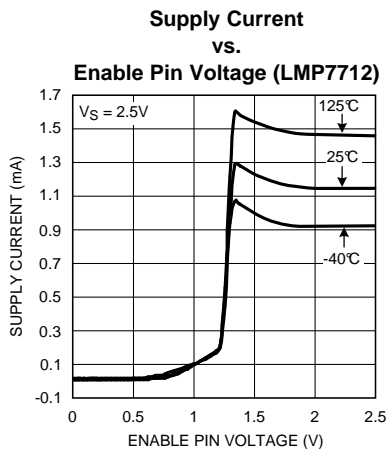
Typical Performance Characteristics (continued)

Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.



Typical Performance Characteristics (continued)

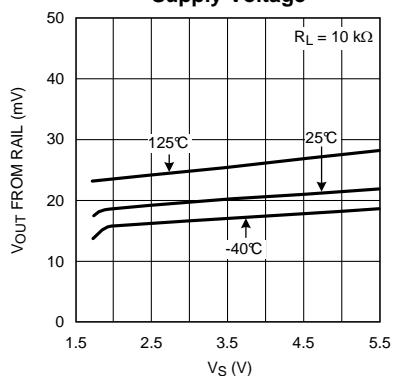
Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.



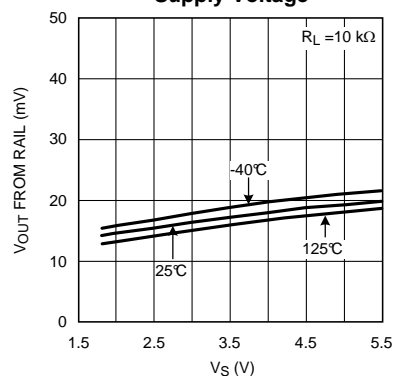
Typical Performance Characteristics (continued)

Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.

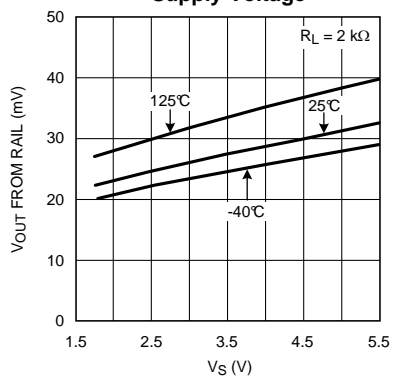
**Output Swing High
vs.
Supply Voltage**



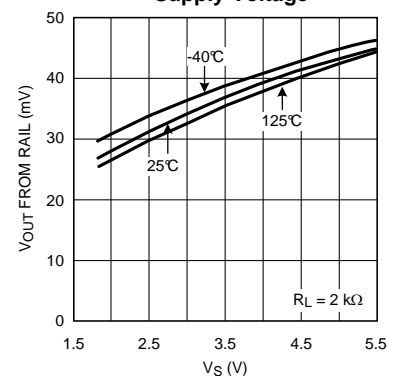
**Output Swing Low
vs.
Supply Voltage**



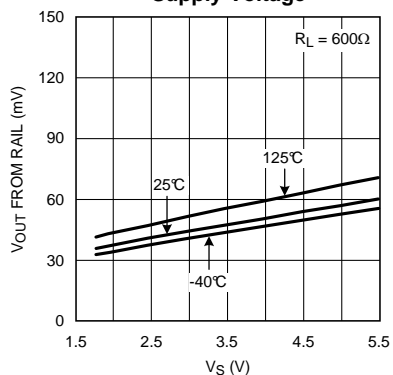
**Output Swing High
vs.
Supply Voltage**



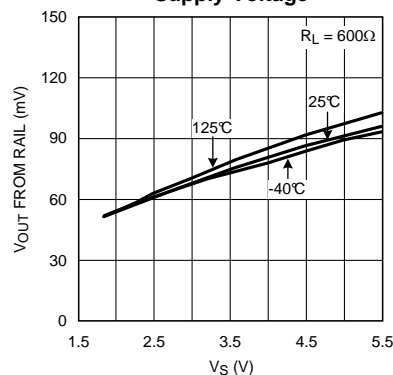
**Output Swing Low
vs.
Supply Voltage**



**Output Swing High
vs.
Supply Voltage**

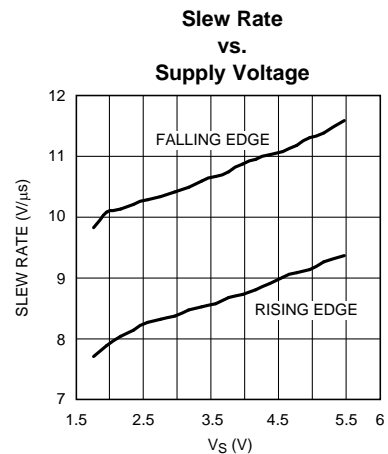
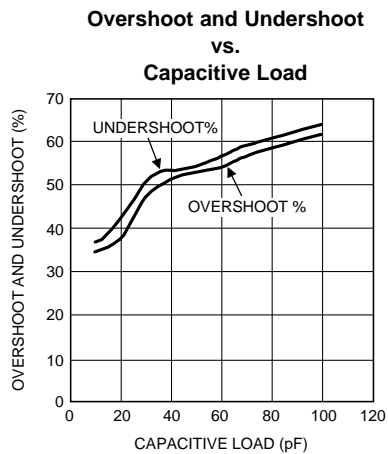
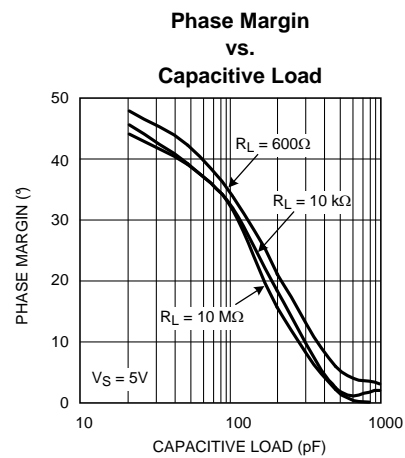
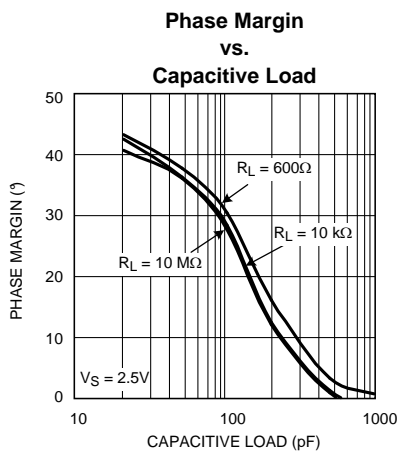
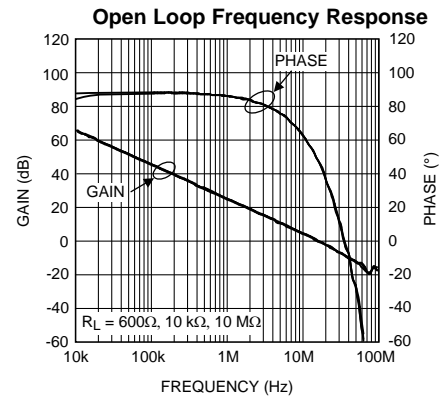
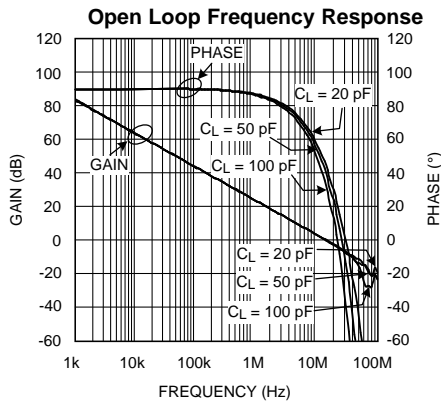


**Output Swing Low
vs.
Supply Voltage**



Typical Performance Characteristics (continued)

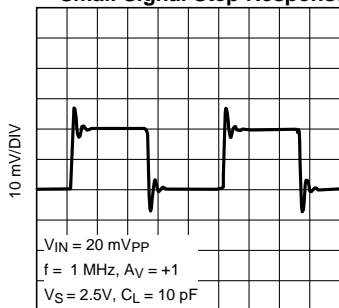
Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.



Typical Performance Characteristics (continued)

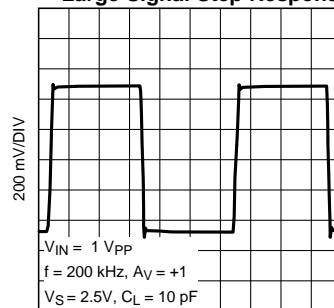
Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.

Small Signal Step Response



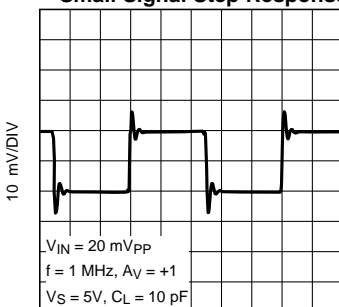
200 ns/DIV

Large Signal Step Response



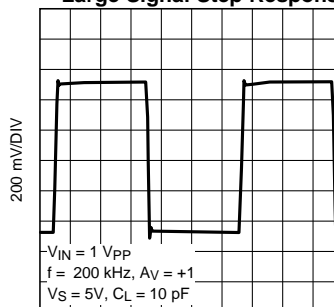
800 ns/DIV

Small Signal Step Response



200 ns/DIV

Large Signal Step Response

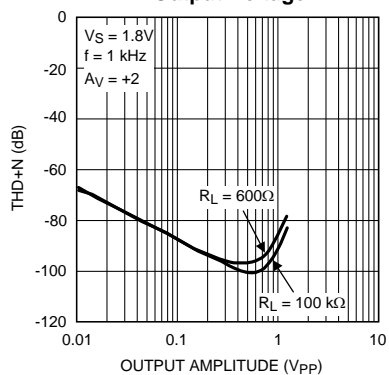


800 ns/DIV

THD+N

vs.

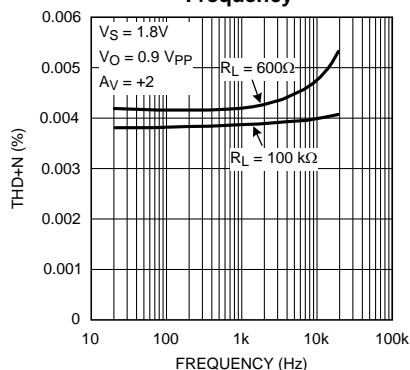
Output Voltage



THD+N

vs.

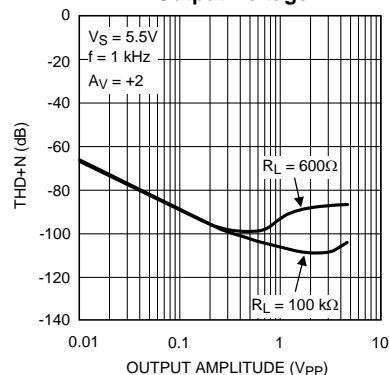
Frequency



THD+N

vs.

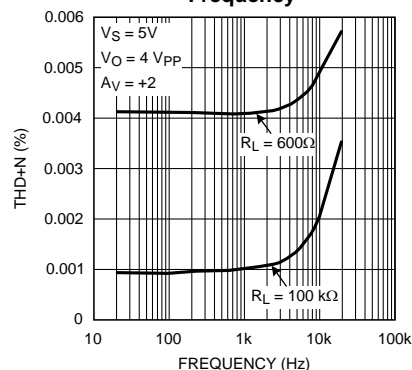
Output Voltage



THD+N

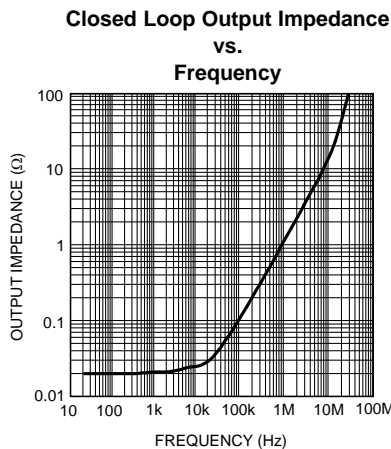
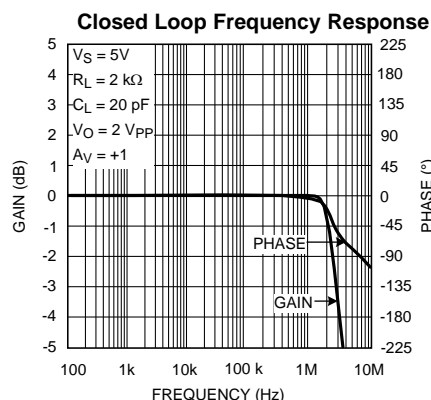
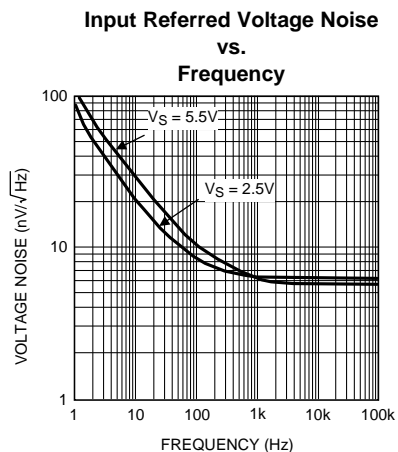
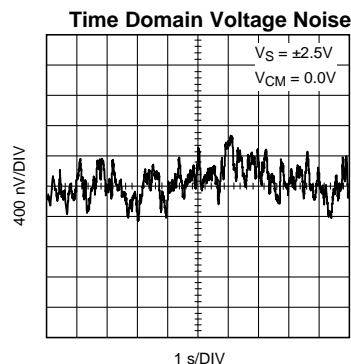
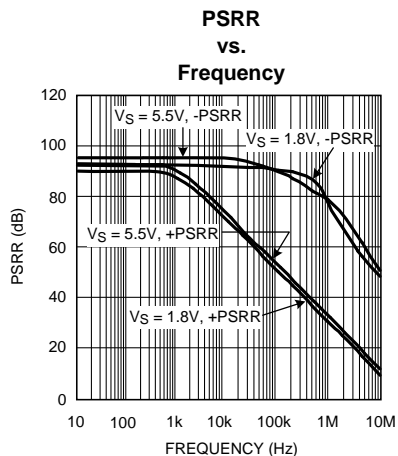
vs.

Frequency



Typical Performance Characteristics (continued)

Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V_{CM} = V_S/2$, $V_{EN} = V^+$.



Application Notes

LMP7711/LMP7712

The LMP7711/LMP7712 are single and dual, low noise, low offset, rail-to-rail output precision amplifiers with a wide gain bandwidth product of 17 MHz and low supply current. The wide bandwidth makes the LMP7711/LMP7712 ideal choices for wide-band amplification in portable applications. The low supply current along with the enable feature that is built-in on the LMP7711/LMP7712 allows for even more power efficient designs by turning the device off when not in use.

The LMP7711/LMP7712 are superior for sensor applications. The very low input referred voltage noise of only $5.8 \text{ nV}/\sqrt{\text{Hz}}$ at 1 kHz and very low input referred current noise of only $10 \text{ fA}/\sqrt{\text{Hz}}$ mean more signal fidelity and higher signal-to-noise ratio.

The LMP7711/LMP7712 have a supply voltage range of 1.8V to 5.5V over a wide temperature range of 0°C to 125°C . This is optimal for low voltage commercial applications. For applications where the ambient temperature might be less than 0°C , the LMP7711/LMP7712 are fully operational at supply voltages of 2.0V to 5.5V over the temperature range of -40°C to 125°C .

The outputs of the LMP7711/LMP7712 swing within 25 mV of either rail providing maximum dynamic range in applications requiring low supply voltage. The input common mode range of the LMP7711/LMP7712 extends to 300 mV below ground. This feature enables users to utilize this device in single supply applications.

The use of a very innovative feedback topology has enhanced the current drive capability of the LMP7711/LMP7712, resulting in sourcing currents as much as 47 mA with a supply voltage of only 1.8V.

The LMP7711 is offered in the space saving TSOT23 package and the LMP7712 is offered in a 10-pin MSOP. These small packages are ideal solutions for applications requiring minimum PC board footprint.

National Semiconductor is heavily committed to precision amplifiers and the market segments they serves. Technical support and extensive characterization data is available for sensitive applications or applications with a constrained error budget.

CAPACITIVE LOAD

The unity gain follower is the most sensitive configuration to capacitive loading. The combination of a capacitive load placed directly on the output of an amplifier along with the output impedance of the amplifier creates a phase lag which in turn reduces the phase margin of the amplifier. If phase margin is significantly reduced, the response will be either underdamped or the amplifier will oscillate.

The LMP7711/LMP7712 can directly drive capacitive loads of up to 120 pF without oscillating. To drive heavier capacitive loads, an isolation resistor, R_{ISO} in Figure 5, should be used. This resistor and C_L form a pole and hence delay the phase lag or increase the phase margin of the overall system. The larger the value of R_{ISO} , the more stable the output voltage will be. However, larger values of R_{ISO} result in reduced output swing and reduced output current drive.

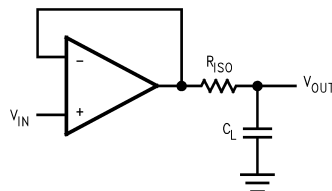


Figure 5. Isolating Capacitive Load

INPUT CAPACITANCE

CMOS input stages inherently have low input bias current and higher input referred voltage noise. The LMP7711/LMP7712 enhance this performance by having the low input bias current of only 50 fA, as well as, a very low input referred voltage noise of $5.8 \text{ nV}/\sqrt{\text{Hz}}$. In order to achieve this a larger input stage has been used. This larger input stage increases the input capacitance of the LMP7711/LMP7712. Figure 6 shows typical input common mode input capacitance of the LMP7711/LMP7712.

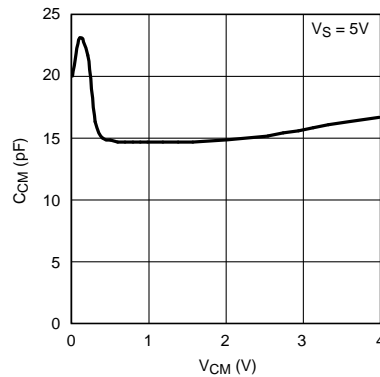


Figure 6. Input Common Mode Capacitance

This input capacitance will interact with other impedances such as gain and feedback resistors, which are seen on the inputs of the amplifier to form a pole. This pole will have little or no effect on the output of the amplifier at low frequencies and under DC conditions, but will play a bigger role as the frequency increases. At higher frequencies, the presence of this pole will decrease phase margin and also causes gain peaking. In order to compensate for the input capacitance, care must be taken in choosing feedback resistors. In addition to being selective in picking values for the feedback resistor, a capacitor can be added to the feedback path to increase stability.

The DC gain of the circuit shown in Figure 7 is simply $-R_2/R_1$.

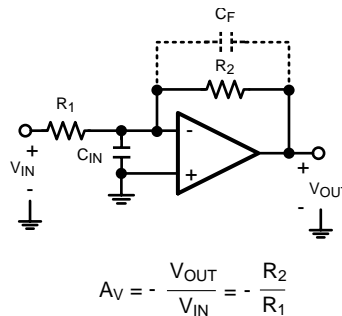


Figure 7. Compensating for Input Capacitance

For the time being, ignore C_F . The AC gain of the circuit in Figure 7 can be calculated as follows:

$$\frac{V_{OUT}}{V_{IN}}(s) = \frac{-R_2/R_1}{1 + \frac{s}{\left(\frac{A_0 R_1}{R_1 + R_2}\right)} + \frac{s^2}{\left(\frac{A_0}{C_{IN} R_2}\right)}} \quad (1)$$

This equation is rearranged to find the location of the two poles:

$$P_{1,2} = \frac{-1}{2C_{IN}} \left[\frac{1}{R_1} + \frac{1}{R_2} \pm \sqrt{\left(\frac{1}{R_1} + \frac{1}{R_2}\right)^2 - \frac{4 A_0 C_{IN}}{R_2}} \right] \quad (2)$$

As shown in Equation 2, as the values of R_1 and R_2 are increased, the magnitude of the poles are reduced, which in turn decreases the bandwidth of the amplifier. Figure 8 shows the frequency response with different value resistors for R_1 and R_2 . Whenever possible, it is best to choose smaller feedback resistors.

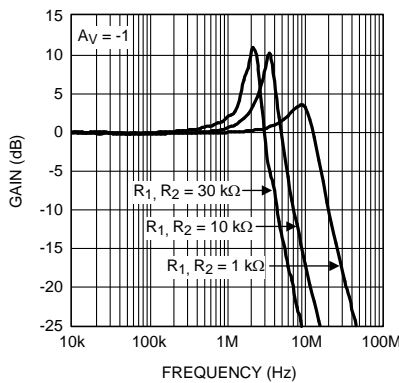


Figure 8. Closed Loop Frequency Response

As mentioned before, adding a capacitor to the feedback path will decrease the peaking. This is because C_F will form yet another pole in the system and will prevent pairs of poles, or complex conjugates from forming. It is the presence of pairs of poles that cause the peaking of gain. Figure 9 shows the frequency response of the schematic presented in Figure 7 with different values of C_F . As can be seen, using a small value capacitor significantly reduces or eliminates the peaking.

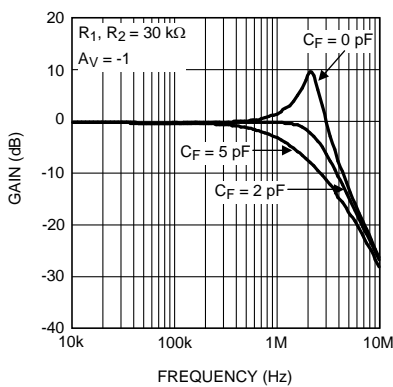


Figure 9. Closed Loop Frequency Response

TRANSIMPEDANCE AMPLIFIER

In many applications, the signal of interest is a very small amount of current that needs to be detected. Current that is transmitted through a photodiode is a good example. Barcode scanners, light meters, fiber optic receivers, and industrial sensors are some typical applications utilizing photodiodes for current detection. This current needs to be amplified before it can be further processed. This amplification is performed using a current-to-voltage converter configuration or transimpedance amplifier. The signal of interest is fed to the inverting input of an op amp with a feedback resistor in the current path. The voltage at the output of this amplifier will be equal to the negative of the input current times the value of the feedback resistor. Figure 10 shows a transimpedance amplifier configuration. C_D represents the photodiode parasitic capacitance and C_{CM} denotes the common-mode capacitance of the amplifier. The presence of all of these capacitances at higher frequencies might lead to less stable topologies at higher frequencies. Care must be taken when designing a transimpedance amplifier to prevent the circuit from oscillating.

With a wide gain bandwidth product, low input bias current and low input voltage and current noise, the LMP7711/LMP7712 are ideal for wideband transimpedance applications.

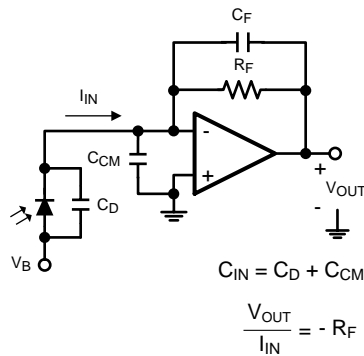


Figure 10. Transimpedance Amplifier

A feedback capacitance C_F is usually added in parallel with R_F to maintain circuit stability and to control the frequency response. To achieve a maximally flat, 2nd order response, R_F and C_F should be chosen by using [Equation 3](#)

$$C_F = \sqrt{\frac{C_{IN}}{GBWP * 2 \pi R_F}} \quad (3)$$

Calculating C_F from [Equation 3](#) can sometimes result in capacitor values which are less than 2 pF. This is especially the case for high speed applications. In these instances, its often more practical to use the circuit shown in [Figure 11](#) in order to allow more sensible choices for C_F . The new feedback capacitor, C'_F , is $(1 + R_B/R_A) C_F$. This relationship holds as long as $R_A \ll R_F$.

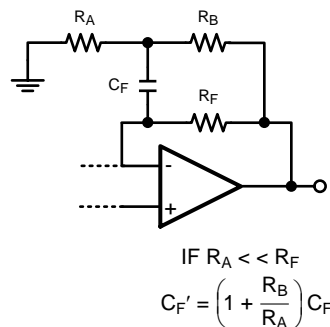


Figure 11. Modified Transimpedance Amplifier

SENSOR INTERFACE

The LMP7711/LMP7712 have low input bias current and low input referred noise, which make them ideal choices for sensor interfaces such as thermopiles, Infra Red (IR) thermometry, thermocouple amplifiers, and pH electrode buffers.

Thermopiles generate voltage in response to receiving radiation. These voltages are often only a few microvolts. As a result, the operational amplifier used for this application needs to have low offset voltage, low input voltage noise, and low input bias current. [Figure 12](#) shows a thermopile application where the sensor detects radiation from a distance and generates a voltage that is proportional to the intensity of the radiation. The two resistors, R_A and R_B , are selected to provide high gain to amplify this signal, while C_F removes the high frequency noise.

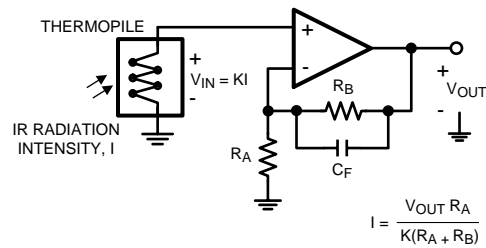


Figure 12. Thermopile Sensor Interface

PRECISION RECTIFIER

Rectifiers are electrical circuits used for converting AC signals to DC signals. Figure 13 shows a full-wave precision rectifier. Each operational amplifier used in this circuit has a diode on its output. This means for the diodes to conduct, the output of the amplifier needs to be positive with respect to ground. If V_{IN} is in its positive half cycle then only the output of the bottom amplifier will be positive. As a result, the diode on the output of the bottom amplifier will conduct and the signal will show at the output of the circuit. If V_{IN} is in its negative half cycle then the output of the top amplifier will be positive, resulting in the diode on the output of the top amplifier conducting and, delivering the signal on the amplifier's output to the circuit's output.

For $R_2/R_1 \geq 2$, the resistor values can be found by using the equation shown in Figure 13. If $R_2/R_1 = 1$, then R_3 should be left open, no resistor needed, and R_4 should simply be shorted.

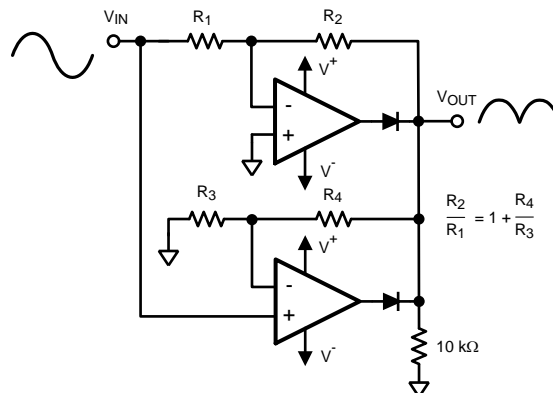


Figure 13. Precision Rectifier

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LMP7711MK	ACTIVE	SOT	DDC	6	1000	TBD	CU SNPB	Level-1-260C-UNLIM	
LMP7711MK/NOPB	ACTIVE	SOT	DDC	6	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMP7711MKE/NOPB	ACTIVE	SOT	DDC	6	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMP7711MKX	ACTIVE	SOT	DDC	6	3000	TBD	CU SNPB	Level-1-260C-UNLIM	
LMP7711MKX/NOPB	ACTIVE	SOT	DDC	6	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMP7712MM/NOPB	ACTIVE	VSSOP	DGS	10	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMP7712MME/NOPB	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMP7712MMX	ACTIVE	VSSOP	DGS	10	3500	TBD	CU SNPB	Level-1-260C-UNLIM	
LMP7712MMX/NOPB	ACTIVE	VSSOP	DGS	10	3500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMP7711MK	SOT	DDC	6	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7711MK/NOPB	SOT	DDC	6	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7711MKE/NOPB	SOT	DDC	6	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7711MKX	SOT	DDC	6	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7711MKX/NOPB	SOT	DDC	6	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7712MM/NOPB	VSSOP	DGS	10	1000	178.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LMP7712MME/NOPB	VSSOP	DGS	10	250	178.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LMP7712MMX	VSSOP	DGS	10	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LMP7712MMX/NOPB	VSSOP	DGS	10	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMP7711MK	SOT	DDC	6	1000	203.0	190.0	41.0
LMP7711MK/NOPB	SOT	DDC	6	1000	203.0	190.0	41.0
LMP7711MKE/NOPB	SOT	DDC	6	250	203.0	190.0	41.0
LMP7711MKX	SOT	DDC	6	3000	206.0	191.0	90.0
LMP7711MKX/NOPB	SOT	DDC	6	3000	206.0	191.0	90.0
LMP7712MM/NOPB	VSSOP	DGS	10	1000	203.0	190.0	41.0
LMP7712MME/NOPB	VSSOP	DGS	10	250	203.0	190.0	41.0
LMP7712MMX	VSSOP	DGS	10	3500	349.0	337.0	45.0
LMP7712MMX/NOPB	VSSOP	DGS	10	3500	349.0	337.0	45.0

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE

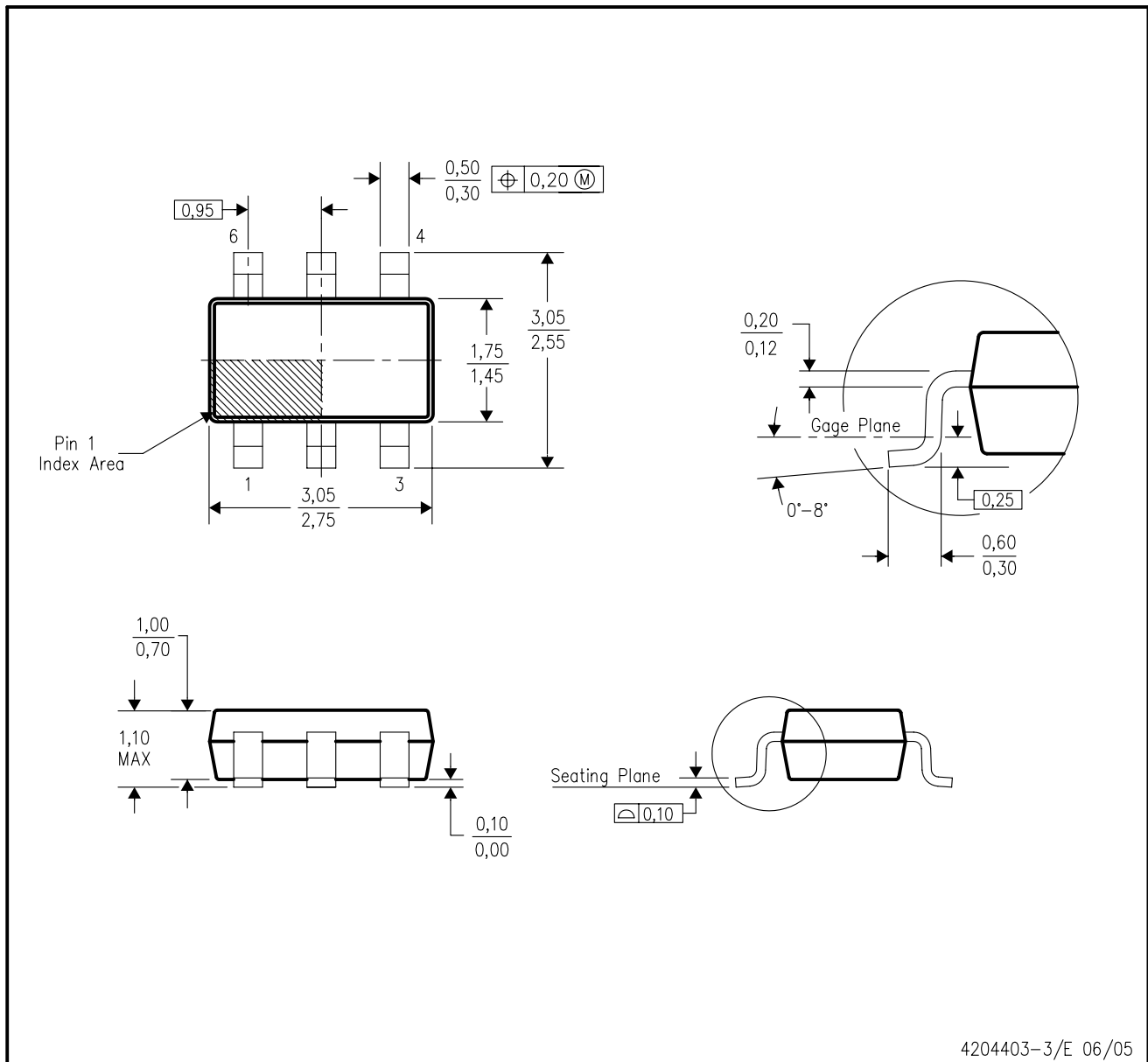


4073272/C 02/04

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-187 variation BA.

DDC (R-PDSO-G6)

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-193 variation AA (6 pin).

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com